

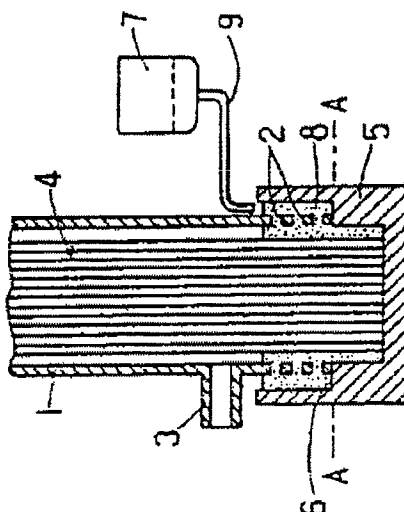
HOLLOW YARN MEMBRANE MODULE AND ITS PREPARATION

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Abstract of JP61222510

PURPOSE: To prevent the release of a resin layer from an outer cylinder by strongly adhering the resin layer to an outer cylinder, by integrating the resin layer fixing a hollow yarn membrane bundle to the outer cylinder through piercing holes provided in the vicinity of both ends of the outer cylinder with the resin layer provided to the outside of the outer cylinder. **CONSTITUTION:** A hollow yarn membrane bundle 4 closed at both ends by heat sealing is inserted in an outer cylinder 1 having a large number of piercing holes 2 provided to both ends thereof so as to protrude the both ends of the yarn membrane bundle 4 from both ends of the outer cylinder 1 and the lower end part of the outer cylinder 1 is covered with a cap 5 having a step part 6 provided to the inner periphery thereof and a liquid injection molding grade resin 8 is injected in the cap 5 from a container 7 through a tube 9. The resin is flowed in the outer cylinder 1 from the piercing holes 2 to fill the space between the outer cylinder 1 and the hollow yarn membrane bundle 4, between yarn membranes and between the outside of the outer cylinder 1 and the inner surface of the cap 5. After the resin 8 was cured, the cap 5 is detached and the end part of the hollow yarn membrane bundle 4 is cut along with the resin 8 to open the membrane end parts of said membrane bundle 4. Next, the upper side of the bundle 4 is directed downwardly to receive the same operation. By this method, the release of the resin is not generated even in a cooling process after high temp. sterilization.



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